

Model LH838 Automatic Back Grinding Wafer Detaper

Feature

- Detaping Procedure: Two different procedures to remove tape of thin and thick wafer.
- Wafer Handler: Laser guided detection.
Misplaced wafer in cross slot is detected and alarm on.
To prevent wafer breakage, handler fork is cleared of cassette during cassette indexing between slots.
Wafer centering and flat/notch detected by laser sensor.
High accuracy XYθ motion, XY resolution at 0.0004", θ resolution at 0.1125°.
No conversion required between different wafer size.
- Fast Conversion: 1 minute between converting different wafer size.
- ESD Protection: 2 Ionizers are installed beneath the adhesive tape and above wafer chamber to remove any static charge generated.
- Machine Safety: Doors are interlocked with EMO.
- Vacuum Source: Build-in high efficiency vacuum generator with auto switching for different wafer size. No need for line vacuum facilities.
- No of Cassette: Dual cassette in horizontal, allowing loading/unloading of cassette without stopping machine.
- Control: Standard industrial PC.
Easy to use menu programming.
Almost unlimited hard disk and floppy disk storage.
Color monitor display.

Specification

- Wafer Size: 4", 5", 6" and 8".
- Wafer Thickness: 6 –30 mil. (150 – 750 micron
- Tape Width: 1.5" to 4" width (38 to 100 mm)
- Tape Length: 100 M.
- Tape Type: Removing tape.

- Wafer Alignment Sensor: Non contact laser sensor.
- Chuck Temperature: Room temperature to 150° C.
- Capacity: 90-120 UPH.
- Power: 220V AC 50/60 Hz. 15A
- Compressed Air: 60 psi dry clean air, 2.5 CFM.
- Dimension: 1100 mm (W) x 1100 mm (D) x 1600 mm (H).
- Net Weight: 400 Kg.